



## Material Content Data Sheet



<b>Sales Product Name</b>		IPP093N06N3 G		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000957262						
<b>Package</b>		PG-TO220-3-1		<b>Weight*</b>		2030.28 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.120	0.10	0.10	1044	1044
leadframe	non noble metal	iron	7439-89-6	1.407	0.07		693	
	inorganic material	phosphorus	7723-14-0	0.422	0.02		208	
	non noble metal	copper	7440-50-8	1404.801	69.20	69.29	691925	692826
wire	non noble metal	aluminium	7429-90-5	2.813	0.14	0.14	1385	1385
encapsulation	organic material	carbon black	1333-86-4	5.955	0.29		2933	
	plastics	epoxy resin	-	113.141	5.57		55727	
	inorganic material	silicondioxide	60676-86-0	476.385	23.46	29.32	234640	293300
leadfinish	non noble metal	tin	7440-31-5	21.462	1.06	1.06	10571	10571
plating	non noble metal	nickel	7440-02-0	0.244	0.01		120	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	0	120
solder	non noble metal	antimony	7440-36-0	0.153	0.01		75	
	noble metal	silver	7440-22-4	0.383	0.02		189	
	non noble metal	tin	7440-31-5	0.996	0.05	0.08	490	754
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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